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a floating base disposed within the body, the floating base coming into contact with the semiconductor device and providing movement of the semiconductor device to alleviate unwanted pressure from the plurality of pins;
a plurality of pogo-pins adjacent to one another, each pogo-pin comprising a cylindrical chamber and a plunger having a crown top at both ends, one end for directly contacting a pin of the semiconductor device and the other end for contacting external test equipment; and
a back panel removably attached to the body.

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19. (amended) The semiconductor device of Claim 18 wherein a series of sets of contact marks result from the testing of the semiconductor device in a test socket comprising a plurality of pogo-pins having a crown portion with pointed ends for directly contacting the plurality of pins of the semiconductor device, the pointed ends having the predetermined pitch.

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21. (amended) A method of testing a semiconductor device having a plurality of pins, the method comprising:

providing a test socket having a body for receiving a semiconductor device, the test socket including a plurality of guide posts integrally formed within the body and a plurality of pogo-pins adjacent to one another for directly contacting the plurality of pins;

aligning the semiconductor device within the body utilizing the guide posts;
applying a pressure which brings the plurality of semiconductor device pins into contact with the plurality of pogo-pins; and
testing the semiconductor device.

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.